



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-02-20
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
USBLC6-2SC6	8BWB*USB2A6A	A	998G	2017-02-20
Amount	UoM	Unit type	ST ECOPACK Grade	
14.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.9-1.625-1.175	6	gull wing	
Comment	SOT 23 - 6L			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8BWB*USB2A6A					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.419	mg	supplier	die	Silicon (Si)	7440-21-3		0.408	mg	973810	29214
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	14286	429
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	4762	143
				supplier	Passivation	Silicon Oxide	7631-86-9		0.003	mg	7143	214
				supplier	alloy	Copper (Cu)	7440-50-8		6.519	mg	976629	465643
Leadframe	Copper & its alloys	6.675	mg	supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.007	mg	1049	500
				supplier	metallization	Silver (Ag)	7440-22-4		0.149	mg	22322	10643
				supplier	glue	Silver (Ag)	7440-22-4		0.131	mg	813665	9357
				supplier	glue	Acrylate resins	7534-94-3		0.019	mg	118012	1357
Die attach	Other Organic Materials	0.161	mg	supplier	glue	Heterocyclic organic compound	3006-93-7		0.005	mg	31056	357
				supplier	glue	Fluoroaliphatic Polymeric Esters	1017237-78-3		0.001	mg	6211	71
				supplier	glue	Treated silica	Proprietary		0.005	mg	31056	357
				supplier	wire	Copper (Cu)	7440-50-8		0.079	mg	1000000	5643
Bonding wires	Other inorganic materials	0.079	mg	supplier	wire	Copper (Cu)	7440-50-8		0.079	mg	1000000	5643
Encapsulation	Other Organic Materials	6.317	mg	supplier	mold compound	Silica, vitreous	60676-86-0		5.457	mg	863859	389786
				supplier	mold compound	Epoxy Resin	25068-38-6		0.474	mg	75036	33857
				supplier	mold compound	Phenol Resin	29690-82-2		0.316	mg	50024	22571
				supplier	mold compound	β-Mercaptopropyl trimethoxysilane	4420-74-0		0.032	mg	5066	2286
				supplier	mold compound	Quartz	14808-60-7		0.019	mg	3008	1357
Connections coating	Solder	0.349	mg	supplier	mold compound	Carbon black	1333-86-4		0.019	mg	3008	1357
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.349	mg	1000000	24929